# KW DMLN33.SG

#### SYNIOS® P2720

KW DMLN33.SG is part of the SYNIOS P2720 family. Given the scalability of this product family, it provides full performance and flexibility with just one footprint. With its improved homogeneity it is meant to provide superior light quality for most application conditions.



#### **Applications**

- Headlamps, LED & Laser & Night Vision

#### **Features:**

- Package: SMD epoxy package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.32, Cy = 0.33 acc. to CIE 1931 (• white)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified with RV-level 1
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

- Signalling





# Ordering Information

Туре	Luminous Flux <sup>1)</sup> I <sub>F</sub> = 200 mA Φ <sub>V</sub>	Ordering Code
KW DMLN33.SG-7J7K-ebvFfcbB46-8E8G	56 100 lm	Q65112A3768



# **Maximum Ratings**

Parameter	Symbol		Values
Operating Temperature	T <sub>op</sub>	min.	-40 °C
	°P	max.	125 °C
Storage Temperature	T <sub>stg</sub>	min.	-40 °C
	0.9	max.	125 °C
Junction Temperature	Tj	max.	150 °C
Junction Temperature for short time applications	Tj	max.	175 °C
Forward Current	I <sub>F</sub>	min.	5 mA
T <sub>s</sub> = 25 °C		max.	300 mA
Surge Current	I <sub>FS</sub>	max.	750 mA
t ≤ 10 μs; D = 0.005 ; T <sub>s</sub> = 25 °C			
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	$V_{ESD}$		8 kV
Reverse current <sup>2)</sup>	I <sub>R</sub>	max.	200 mA

\* The median lifetime (L70/B50) for Tj =  $175^{\circ}$ C is 100h.



## **Characteristics**

 $I_{_{
m F}}$  = 200 mA;  $T_{_{
m S}}$  = 25 °C

Parameter	Symbol		Values	
Chromaticity Coordinate 3)	Cx Cy	typ. typ.	0.32 0.33	
Viewing angle at 50% $\rm I_v$	2φ	typ.	120 °	
Forward Voltage <sup>4)</sup> I <sub>F</sub> = 200 mA	V <sub>F</sub>	min. typ. max.	2.75 V 3.00 V 3.50 V	
Reverse voltage (ESD device)	V <sub>r esd</sub>	min.	45 V	
Reverse voltage <sup>2)</sup> I <sub>R</sub> = 20 mA	V <sub>R</sub>	max.	1.2 V	
Real thermal resistance junction/solderpoint <sup>5)</sup>	$R_{thJS real}$	typ. max.	18 K / W 20 K / W	
Electrical thermal resistance junction/solderpoint $^{\rm 5)}$ with efficiency $\eta_{\rm e}$ = 30 %	$R_{thJSelec.}$	typ. max.	13 K / W 14 K / W	



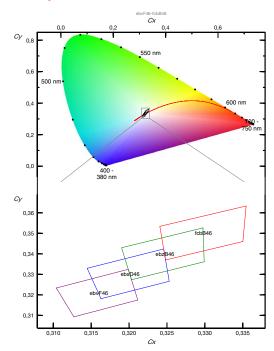
# **Brightness Groups**

Group	Luminous Flux <sup>1)</sup> I <sub>F</sub> = 200 mA min. Φ <sub>v</sub>	Luminous Flux <sup>1)</sup> I <sub>F</sub> = 200 mA max. Φ <sub>V</sub>	Luminous Intensity <sup>6)</sup> I <sub>F</sub> = 200 mA typ. I <sub>v</sub>	
7J	56 lm	63 lm	20 cd	
8J	63 lm	71 lm	22 cd	
5K	71 lm	80 lm	25 cd	
6K	80 lm	90 lm	28 cd	
7K	90 lm	100 lm	31 cd	

# Forward Voltage Groups

Group	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 200 mA min. V <sub>F</sub>	Forward Voltage <sup>4)</sup> I <sub>F</sub> = 200 mA max. V <sub>F</sub>	
8E	2.75 V	3.00 V	
8F	3.00 V	3.25 V	
8G	3.25 V	3.50 V	





# Chromaticity Coordinate Groups

# Chromaticity Coordinate Groups <sup>3)</sup>

Сх	Су	Group	Cx	Су
0.3127	0.3093	ebzB46	0.3203	0.3274
0.3212	0.3175		0.3299	0.3361
0.3199	0.3325		0.3298	0.3526
0.3104	0.3234		0.3190	0.3430
0.3163	0.3181	fcbB46	0.3248	0.3370
0.3253	0.3266		0.3350	0.3460
0.3246	0.3424		0.3355	0.3633
0.3145	0.3330		0.3241	0.3534
	0.3127 0.3212 0.3199 0.3104 0.3163 0.3253 0.3246	0.31270.30930.32120.31750.31990.33250.31040.32340.31630.31810.32530.32660.32460.3424	0.3127       0.3093       ebzB46         0.3212       0.3175       ebzB46         0.3199       0.3255       ebzB46         0.3104       0.3234       ebzB46         0.3163       0.3181       fcbB46         0.3253       0.3266       ebzB46	0.3127       0.3093       ebzB46       0.3203         0.3212       0.3175       0.3299         0.3199       0.325       0.3298         0.3104       0.3234       0.3190         0.3163       0.3181       fcbB46       0.3248         0.3253       0.3266       0.3350       0.3355

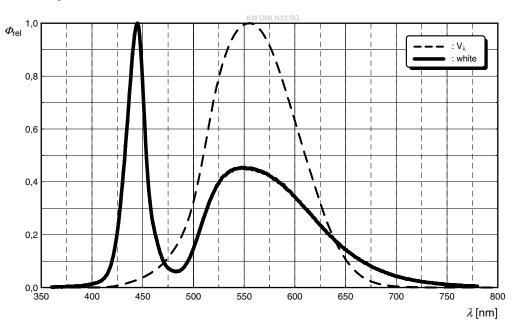


Group Name on Label			
Example: 5K-ebvF46-8E Brightness	Color Chromaticity	Forward Voltage	
5K	ebvF46	8E	



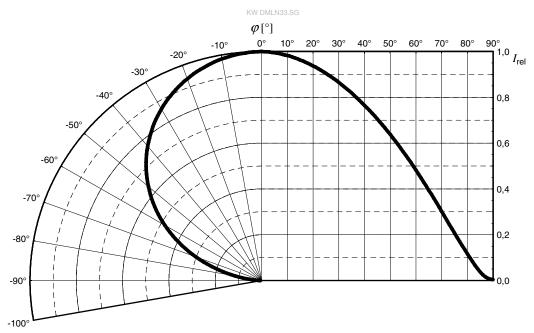
#### **Relative Spectral Emission**<sup>6)</sup>

 $\Phi_{_{rel}}$  = f ( $\lambda$ ); I $_{_F}$  = 200 mA; T $_{_S}$  = 25 °C



## **Radiation Characteristics** <sup>6)</sup>

 $I_{rel} = f(\phi); T_s = 25 \ ^{\circ}C$ 



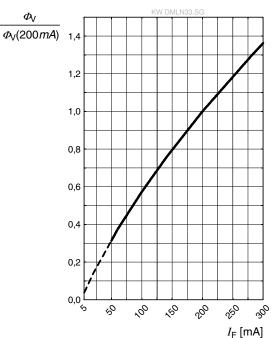


Forward current <sup>6), 7)</sup>

# $I_{F} = f(V_{F}); T_{S} = 25 °C$ $I_{F} [mA]^{30} \xrightarrow{KW DMLN33.SG} \xrightarrow{KW DMLN33.SG} \xrightarrow{I}$

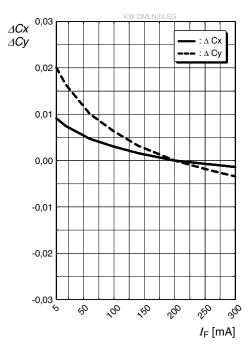
#### Relative Luminous Flux <sup>6), 7)</sup>

 $\Phi_{v}/\Phi_{v}(200 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$ 



## Chromaticity Coordinate Shift <sup>6)</sup>

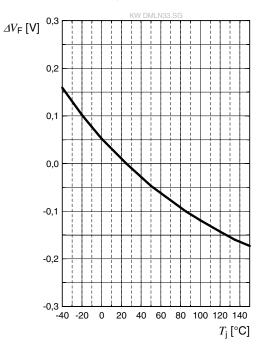
 $\Delta Cx$ ,  $\Delta Cy = f(I_F)$ ;  $T_S = 25 \ ^{\circ}C$ 





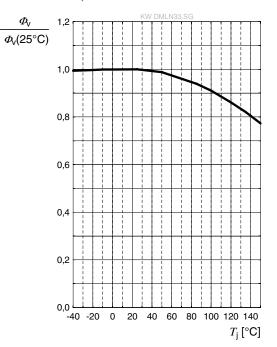
## Forward Voltage <sup>6)</sup>

 $\Delta V_{_F} = V_{_F} - V_{_F}(25 \text{ °C}) = f(T_{_J}); I_{_F} = 200 \text{ mA}$ 



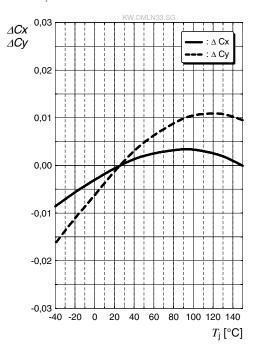
### **Relative Luminous Flux**<sup>6)</sup>

 $\Phi_v/\Phi_v(25 \text{ °C}) = f(T_i); I_F = 200 \text{ mA}$ 



# Chromaticity Coordinate Shift <sup>6)</sup>

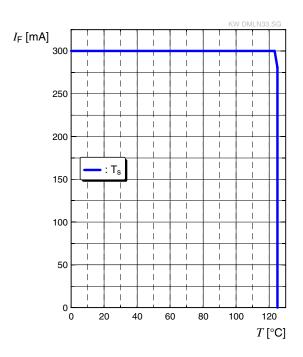
 $\Delta Cx$ ,  $\Delta Cy = f(T_j)$ ;  $I_F = 200 \text{ mA}$ 





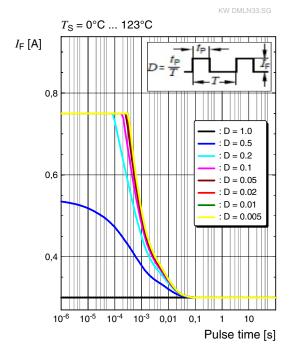
## Max. Permissible Forward Current

 $I_{F} = f(T)$ 



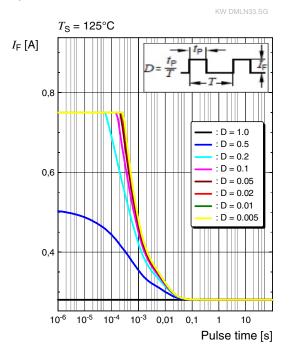
## Permissible Pulse Handling Capability

 $I_{F} = f(t_{p}); D: Duty cycle$ 



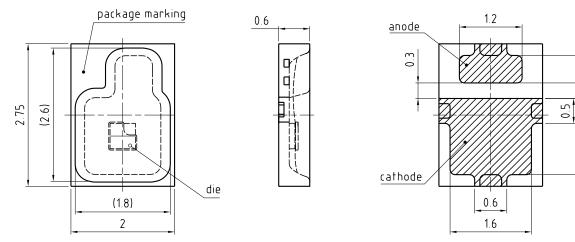
## Permissible Pulse Handling Capability

 $I_{_{P}} = f(t_{_{P}}); D: Duty cycle$ 





# Dimensional Drawing <sup>8)</sup>



General toleran	ice ±0.1
Lead finish Au	

## **Further Information:**

Approximate Weight:	12.0 mg
Corrosion test:	Class: 3B Test condition: 40°C / 90 % RH / 15 ppm H <sub>2</sub> S / 14 days (stricter than IEC 60068-2-43)
ESD advice:	The device is protected by ESD device which is connected in parallel to the Chip.

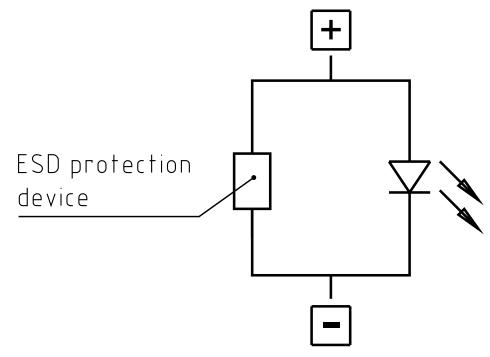


0.5

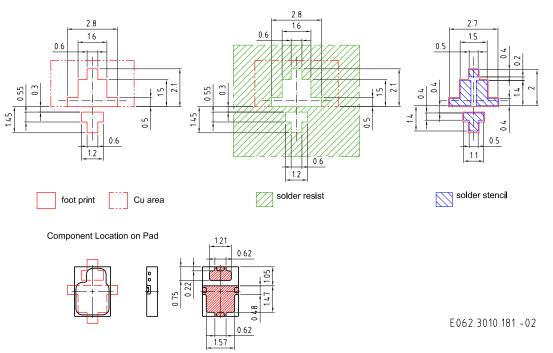
1.5

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## **Electrical Internal Circuit**



#### **Recommended Solder Pad**<sup>8)</sup>

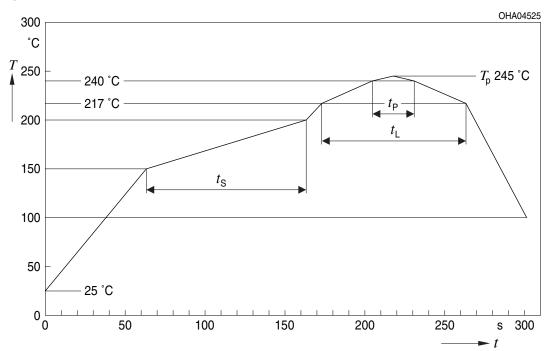


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



## **Reflow Soldering Profile**

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb	-Free (SnAgCu) Assembly		Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat <sup>•)</sup> 25 °C to 150 °C			2	3	K/s
Time t <sub>s</sub> T <sub>smin</sub> to T <sub>smax</sub>	t <sub>s</sub>	60	100	120	S
Ramp-up rate to peak <sup>*)</sup> $T_{smax}$ to $T_{p}$			2	3	K/s
Liquidus temperature	TL		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	T <sub>P</sub>		245	260	°C
Time within 5 °C of the specified peak temperature $T_p$ - 5 K	t <sub>P</sub>	10	20	30	S
Ramp-down rate* T <sub>P</sub> to 100 °C			3	6	K/s
Time 25 °C to T <sub>P</sub>				480	S

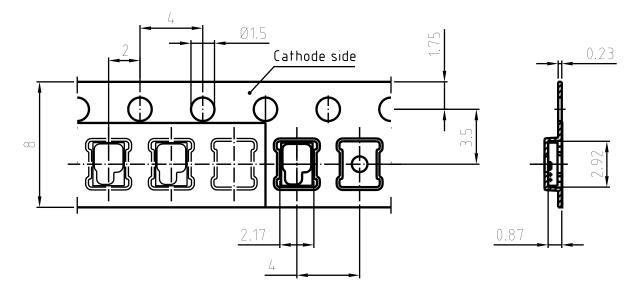
All temperatures refer to the center of the package, measured on the top of the component

 $^{\ast}$  slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



#### KW DMLN33.SG

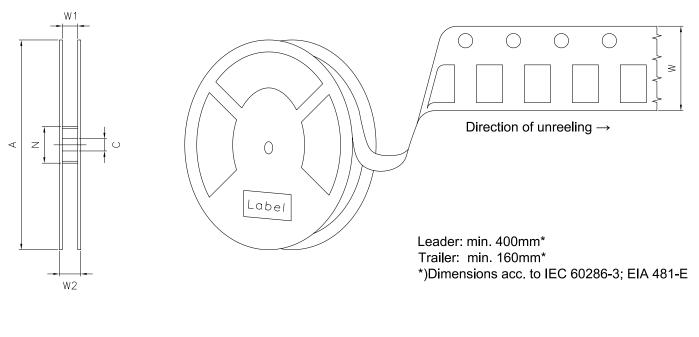
# Taping<sup>8)</sup>



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## Tape and Reel <sup>9)</sup>

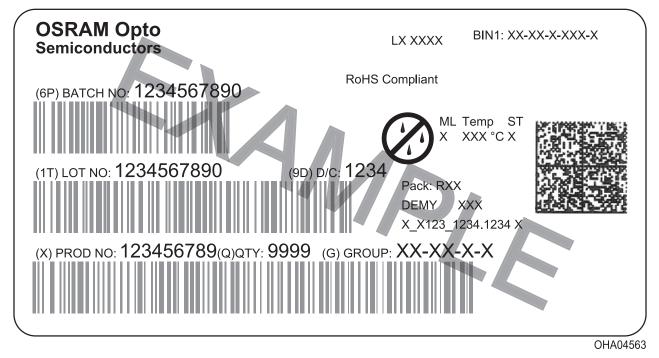


## **Reel Dimensions**

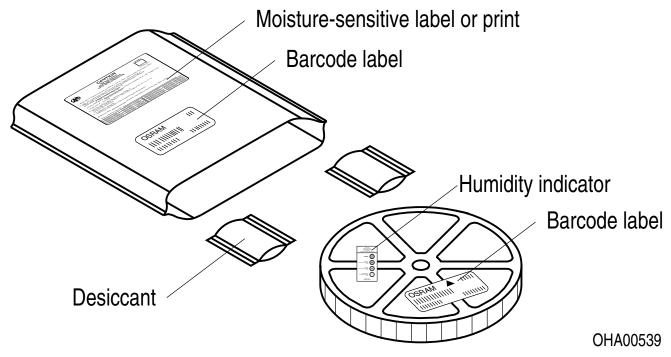
А	W	N <sub>min</sub>	$W_1$	$W_{2 \max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000



#### **Barcode-Product-Label (BPL)**



### Dry Packing Process and Materials<sup>8)</sup>



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



#### **Notes**

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



#### Disclaimer

#### Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

#### Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

#### Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



### Glossary

- <sup>1)</sup> **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 8$  % and an expanded uncertainty of  $\pm 11$  % (acc. to GUM with a coverage factor of k = 3).
- <sup>2)</sup> **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- <sup>3)</sup> **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of  $\pm 0.005$  and an expanded uncertainty of  $\pm 0.01$  (acc. to GUM with a coverage factor of k = 3).
- <sup>4)</sup> **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of  $\pm 0.05$  V and an expanded uncertainty of  $\pm 0.1$  V (acc. to GUM with a coverage factor of k = 3).
- <sup>5)</sup> **Thermal Resistance:** Rth max is based on statistic values ( $6\sigma$ ).
- <sup>6)</sup> **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- <sup>7)</sup> **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- <sup>8)</sup> **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- <sup>9)</sup> **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

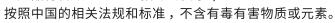


Revision History				
Version	Date	Change		
1.4	2021-02-18	Features Schematic Transportation Box Dimensions of Transportation Box Glossary		



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